

Title (en)

LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE

Title (de)

HEISSSCHMELZENDES HAFTMITTEL MIT GERINGER ANWENDUNGSTEMPERATUR

Title (fr)

ADHÉSIF THERMOFUSIBLE POUR UNE APPLICATION À BASSE TEMPÉRATURE

Publication

EP 2459665 A4 20121219 (EN)

Application

EP 10805084 A 20100730

Priority

- US 23032209 P 20090731
- US 2010043804 W 20100730

Abstract (en)

[origin: WO2011014714A2] High temperature performance hot melt adhesives are formulated for application at low temperatures below, i.e., below 300°F. Hot melt adhesives containing low levels of metallocene polymer together with a maleated polyethylene wax show an excellent balance of high and low temperature performance and are particularly useful as packaging case and carton adhesives.

IPC 8 full level

C09J 5/06 (2006.01); **C09J 123/08** (2006.01); **C09J 123/20** (2006.01); **C09J 191/06** (2006.01)

CPC (source: EP KR US)

C09J 5/06 (2013.01 - KR); **C09J 123/08** (2013.01 - KR); **C09J 123/0815** (2013.01 - EP US); **C09J 123/20** (2013.01 - KR);
C09J 191/06 (2013.01 - EP KR US); **C08L 23/0815** (2013.01 - EP US); **C08L 51/06** (2013.01 - EP US); **C08L 91/06** (2013.01 - EP US);
C08L 2205/02 (2013.01 - EP US); **C08L 2666/02** (2013.01 - EP US); **Y10T 428/13** (2015.01 - EP US); **Y10T 428/1324** (2015.01 - EP US);
Y10T 428/1334 (2015.01 - EP US); **Y10T 428/1352** (2015.01 - EP US); **Y10T 428/1397** (2015.01 - EP US)

Citation (search report)

- [A] WO 0000565 A1 20000106 - FULLER H B LICENSING FINANC [US], et al
- See references of WO 2011014714A2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)

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CN 102471655 A 20120523; CN 102471655 B 20150211; EP 2459665 A2 20120606; EP 2459665 A4 20121219; EP 2459665 B1 20131120;
JP 2013501099 A 20130110; JP 5563081 B2 20140730; KR 101507211 B1 20150330; KR 20120039052 A 20120424;
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DOCDB simple family (application)

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